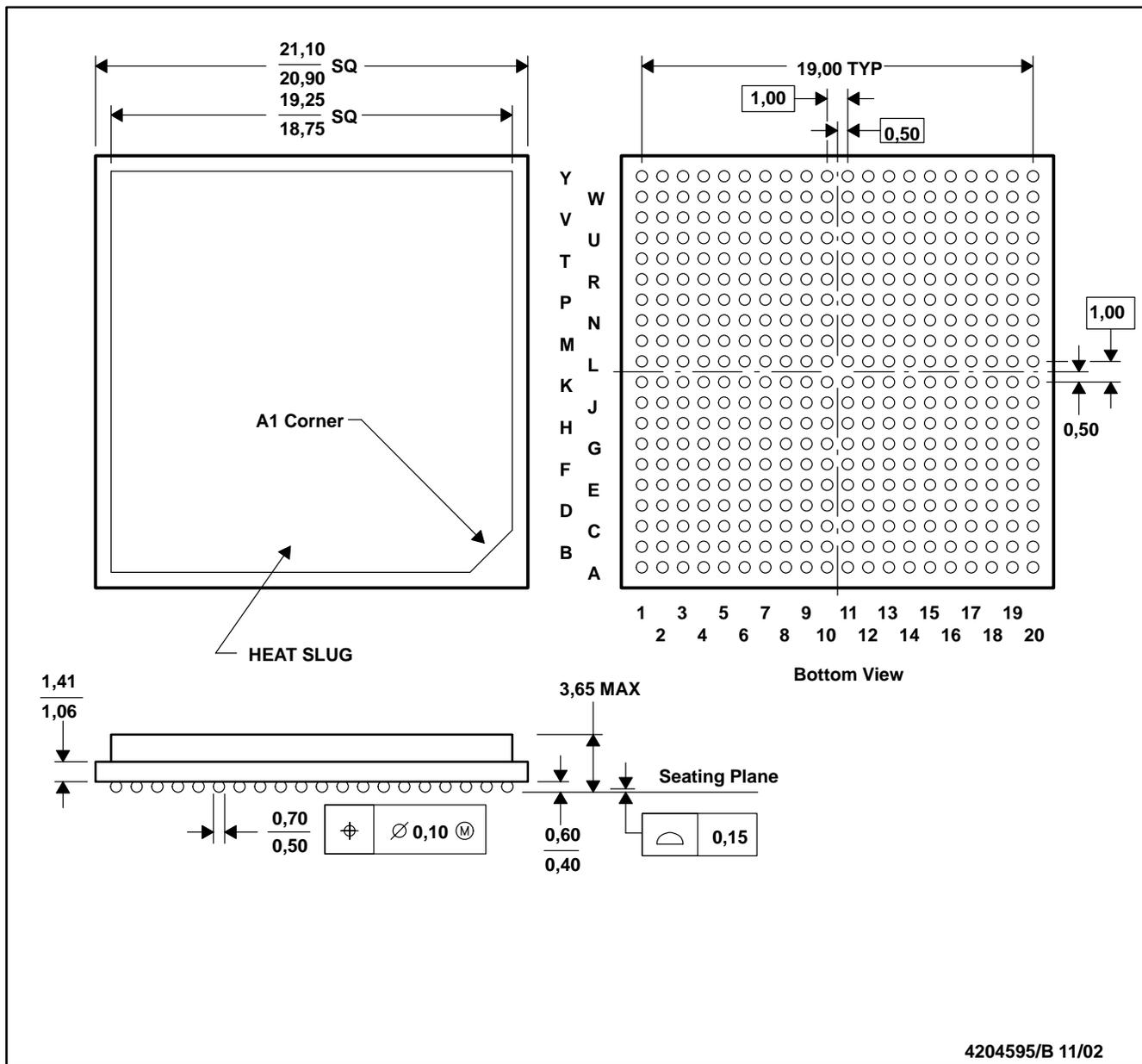


GDV (S-PBGA-N400)

PLASTIC BALL GRID ARRAY



- NOTES: A. All linear dimensions are in millimeters.
 B. This drawing is subject to change without notice.
 C. Thermally enhanced plastic package with heat slug (HSL).
 D. Flip chip application only.

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